

PRODUCT NUMBER

98423-XXX-XXXLF

PLATING

S = 0.38µm GOLD/GXT ON CONTACT AREA
2µm MIN MATTE TIN ON TAIL

G = 0.76µm GOLD/GXT ON CONTACT AREA
2µm MIN MATTE TIN ON TAIL

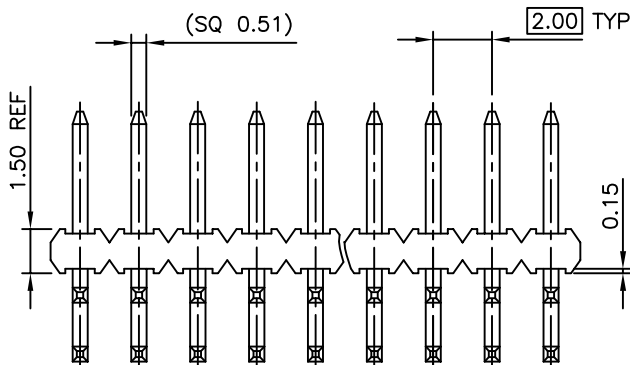
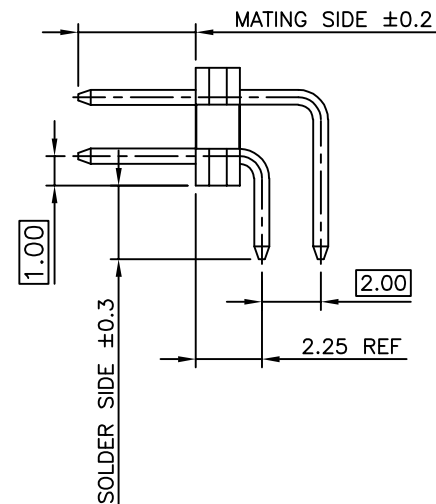
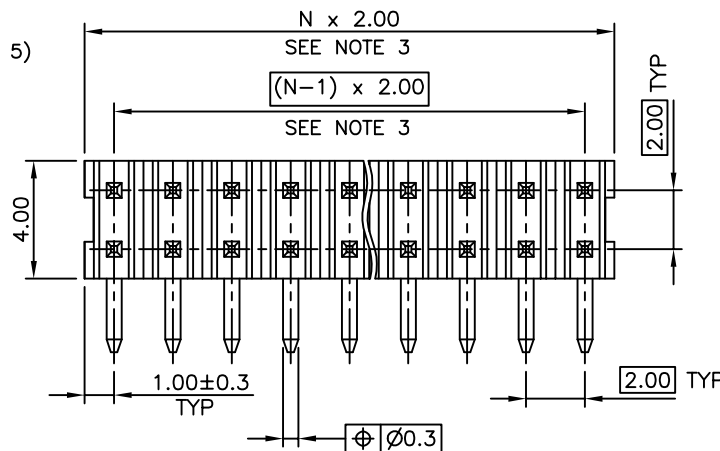
F = GOLD FASH ON CONTACT AREA
2µm MIN MATTE

RoHS COMPATIBLE, SEE NOTE 6

PACKAGING OPTIONAL LETTER (SEE NOTE 5)

NB OF POSITIONS PER ROW
02 TO 25 POS

PIN STYLE	MATING STYLE	SOLDER STYLE
61	4.00	2.50
62	7.00	3.00
63	7.00	3.50



NOTES:

1. MATERIAL HOUSING: HIGH TEMP. THERMOPLASTIC UL 94V-0, COLOR BLACK
2. MATERIAL TERMINAL: COPPER ALLOY

3. TO DETERMINE DIMENSIONS:
N = NUMBER OF POSITIONS PER ROW

4. 7N MIN. PIN RETENTION IN EITHER DIRECTION.

5. PACKAGING:

= PLASTIC BOX

U = TUBE AVAILABLE FROM 06 TO 50 POS

6. RoHS COMPATIBLE PRODUCT SPECIFICATIONS

a - PLATING:

- "LF" MEANS THE PRODUCT IS LEAD-FREE, 2µm MINIMUM MATTE TIN OVER 1.27µm MINIMUM NICKEL UNDERPLATE.

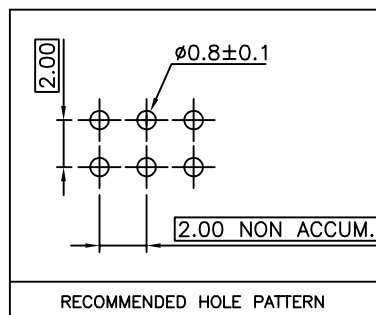
b - MANUFACTURING PROCESS COMPATIBILITY

- THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C ±5°C SOLDER BATH TEMPERATURE FOR 5 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.6mm MIN THICK CIRCUIT BOARD.

c - LABELLING:

- MEETS PACKAGING SPECS AS PER GS-14-920

- THIS PRODUCT MEETS EUROPEAN DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DISCRIBED IN GS-47-0004



mat'l. code		surface ISO 1302		tolerance ISO 406		projection ISO 1101		product family MINITEK	
ltr		ecn no		dr		date		title	
A		F10338		LMU		03.10.01		UNSHR HEADER	
B		F04-035		JCO		05.01.13		RIGHT ANGLE TMT	
C		F06-0210		LMU		06.07.05		scale 1:1	
D		F08-0145		ELA		17.04.08		dr L MULIN 04.09.28	
E		B-19190		LMU		14.10.24		engr J COMPAGNON 04.09.28	
F		F-25393		DDE		16.11.21		chr	
G		F-26943		DDE		17.05.10		appd JM.C 04.09.28	
sheet index		revision sheet						type CUSTOMER Drawing	

